



立敏電子延長 IC 包裝保存期

立敏電子宣布 IC 包裝保存期之一重大改善，將 QFN 封裝產品期限從 2 年延長至 5 年。

經過嚴格的測試，包括在 MFG(Mixed Flowing Gas)環境中暴露 96 小時而產生的老化加速因子(Acceleration Factor)下，證實了 QFN 封裝的可靠性。且成功通過不同的測試項目，包括目視檢查(Visual Inspection)、可焊性(Solderability)、濕潤平衡(Wetting-Balance)和電路板安裝(Board Mount)，並通過長期儲存評估，證實了長時間的可靠度。

立敏電子在品質和客戶滿意度上持續精進，在庫存管理方面提供更大的靈活，同時維持 IC 產品的高可靠性。

如您針對此宣告內容有任何問題，煩請連繫您的當地業務。

RICHNEX EXTENDS SHELF LIFE OF PACKAGED IC PRODUCTS

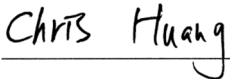
Richnex announces a significant enhancement in the shelf life of packaged IC products, extending it from 2 years to 5 years for all QFN packages.

Rigorous tests, including 96-hour exposure in MFG environment which is known as aging acceleration factors, confirmed the reliability of QFN packages. All tests, covering visual inspection, solderability, wetting-balance, and board mount, passed successfully. Additionally, the QFN products underwent long-term-storage evaluation, affirming their reliability over the extended period.

This shows our dedication to quality and customer satisfaction, offering greater flexibility in inventory management while maintaining high reliability standards in IC solutions.

Should you have any questions regarding this declaration, please contact your local sales representative.

Regards,


2024/6/4

Quality System